Filename: PMP11757RevC - BoM.xls

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## TEXAS INSTRUMENTS

## PMP11757 REV C Bill of Materials

Item #	Designator	Quantity		PartNumber	Manufacturer	Description	PackageReference
1	C1_1, C1_2,	8	22uF	GRM31CR71A226KE15L	MuRata	CAP, CERM, 22 μF, 10 V, +/- 10%, X7R, 1206	1206
	C2_1, C2_2,						
	C11, C19,						
	C20, C101						
2	C3_1, C3_2	2			MuRata	CAP, CERM, 33 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
3	C4_1, C4_2,	8	1uF	GRM188R71E105KA12D	MuRata	CAP, CERM, 1 µF, 25 V, +/- 10%, X7R, 0603	0603
	C5_1, C5_2,						
	C6_1, C6_2,						
	C7_1, C7_2						
4	C8, C9, C17,	4	4.7uF	GRM31CR71H475KA12L	MuRata	CAP, CERM, 4.7 μF, 50 V, +/- 10%, X7R, 1206	1206
	C18						
5	C10, C16	2			MuRata	CAP, CERM, 0.47 µF, 25 V, +/- 10%, X7R, 0603	0603
	C13, C22				MuRata	CAP, CERM, 4.7 μF, 10 V, +/- 10%, X7R, 0805	0805
7	C14	1			MuRata	CAP, CERM, 10 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
8	C15	1			MuRata	CAP, CERM, 0.1 μF, 50 V, +/- 10%, X7R, 0603	0603
9	C21	1			MuRata	CAP, CERM, 56 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
10	FID1, FID2,	4		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	N/A
	FID3, FID4						
11	J1_1, J1_2,	12		61300211121	Wurth Elektronik	Header, 2.54 mm, 2x1, Gold, TH	Header, 2.54mm,
	J3_1, J3_2,						2x1, TH
	J4_1, J4_2,						
	J5_1, J5_2,						
	J6_1, J6_2,						
- 10	J10, J13			242224424	W. 4 E. L. 9	11. 1. 0.74	111 1 0 5 1
12	J2_1, J2_2,	7		61300311121	Wurth Elektronik	Header, 2.54 mm, 3x1, Gold, TH	Header, 2.54mm,
	J7_1, J7_2,						3x1, TH
	J8_1, J8_2, J11						
13	J9, J12	2		ED555/2DS	On-Shore Technology	Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	7.0x8.2x6.5mm
14	L1_1, L1_2	2	6.8uH	LPS4012-682MLB	Coilcraft	Inductor, Shielded Drum Core, Ferrite, 6.8 µH, 0.98 A, 0.34 ohm, SMD	LPS4012
15	L2, L3	2		XAL4020-222MEB	Coilcraft	Inductor, Shielded Dram Cole, 1 emile, 0.0 µm, 0.90 Å, 0.94 omm, SMD	4x2.1x4mm
16	R1_1, R1_2,	4		CRCW060349R9FKEA	Vishay-Dale	RES, 49.9, 1%, 0.1 W, 0603	0603
10	R5, R10	4	<del>-</del> 3.3	ONOWOOD43N3I NEA	visitay-Dale	11CO, 40.0, 170, 0.1 W, 0000	0003
17	R2_1, R2_2,	4	200k	CRCW0603200KFKEA	Vishay-Dale	RES, 200 k, 1%, 0.1 W, 0603	0603
1,	R6, R11			S. COTTOGOZOGICI INEA	Tionay Daio	1120, 200 11, 170, 0.1 11, 0000	
18	R3_1, R3_2	2	22.1k	CRCW060322K1FKEA	Vishay-Dale	RES, 22.1 k, 1%, 0.1 W, 0603	0603
19	R4, R9	2		CRCW06030000Z0EA	Vishay-Dale	RES, 0, 5%, 0.1 W, 0603	0603
10	,			0.10.100000000Z0Z/1	violity Daio	11.20, 0, 070, 011 11, 0000	10000

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
20	R7	1	3.01	CRCW06033R01FKEA	Vishay-Dale	RES, 3.01, 1%, 0.1 W, 0603	0603
21	R8, R12	2	86.6k	CRCW060386K6FKEA	Vishay-Dale	RES, 86.6 k, 1%, 0.1 W, 0603	0603
22	TP1_1, TP1_2, TP3, TP4, TP7, TP8	6	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
23	TP2_1, TP2_2, TP5, TP6, TP9, TP10	6	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
24	U1_1, U1_2	2		TPS61071-Q1	Texas Instruments	90% Efficient Synchronous Boost Converter with 600-mA Switch, DDC0006A	DDC0006A
25	U2_1, U2_2	2		TLV71310-Q1	Texas Instruments	Capacitor-Free, 150-mA, Low-Dropout Regulator with Foldback Current Limit for Portable Devices, DBV0005A	DBV0005A
26	U3_1, U3_2	2		TLV71325-Q1	Texas Instruments	Capacitor-Free, 150-mA, Low-Dropout Regulator with Foldback Current Limit for Portable Devices, DBV0005A	DBV0005A
27	U4	1		LM53602AQPWPRQ1	Texas Instruments	5 V/3.3 V/ADJ, 2 A/3 A, Buck Regulator For Automotive Applications, PWP0016H	PWP0016H
28	U5	1		LMR23625C-Q1	Texas Instruments	SIMPLE SWITCHER 36V 2.5 A Synchronous Step-Down Converter, DDA0008E	DDA0008E

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